

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A surface-mounting type electronic circuit unit comprising:

a side electrode arranged on a side face;
a circuit substrate having a wiring pattern arranged on an upper face in a state connected to thisthe side electrode; and
an electric part connected to said wiring pattern by soldering;
wherein said wiring pattern has a connecting conductor electrically connecting said side electrode and said electric part, and said connecting conductor contains multiple bends between said electric part and said side electrode disconnecting said electric part arranged in a position very near said side electrode is formed in a bent state.

2. (Cancelled)

3. (Currently Amended) A surface-mounting type electronic circuit unit comprising:

a side electrode arranged on a side face;
a circuit substrate having a wiring pattern arranged on an upper face in a state connected to thisthe side electrode; and
an electric part connected to said wiring pattern by soldering;
wherein said wiring pattern has a connecting conductor electrically connecting said side electrode and said electric part, and a layer fabricated by silk screen printing is formed on said connecting conductor connecting between said electric part and arranged in a position very near said side electrode so as to cross thisthe connecting conductor.

4. (Original) The surface-mounting type electronic circuit unit according to claim 3, wherein said connecting conductor is formed in a straight line shape.

5. (Original) The surface-mounting type electronic circuit unit according to claim 3, wherein said connecting conductor is formed in a bent state.

6. (Original) The surface-mounting type electronic circuit unit according to claim 5, wherein said connecting conductor is formed in the bent state of a zigzag shape.

7. (New) The surface-mounting type electronic circuit unit according to claim 1, wherein said connecting conductor has a length sufficient to avoid melting the solder attaching the electric part when the side electrode is soldered to an electrically conductive pattern of a mother substrate.

8. (New) The surface-mounting type electronic circuit unit according to claim 1, wherein said connecting conductor has a U-shaped bend.

9. (New) The surface-mounting type electronic circuit unit according to claim 1, wherein said connecting conductor has a V-shaped bend.

10. (New) The surface-mounting type electronic circuit unit according to claim 1, wherein said connecting conductor has a total bend of at least 180°.

11. (New) The surface-mounting type electronic circuit unit according to claim 3, wherein said connecting conductor has a length sufficient to avoid melting the solder attaching the electric part when the side electrode is soldered to an electrically conductive pattern of a mother substrate.

12. (New) The surface-mounting type electronic circuit unit according to claim 3, wherein said connecting conductor has a U-shaped bend.

13. (New) The surface-mounting type electronic circuit unit according to claim 3, wherein said connecting conductor has a V-shaped bend.

14. (New) The surface-mounting type electronic circuit unit according to claim 3, wherein said connecting conductor has a total bend of at least 180°.

15. (New) A method of fabricating a surface-mounting type electronic circuit unit, the method comprising:

forming a circuit substrate having a wiring pattern arranged on an upper face and a side electrode arranged on a side face, the wiring pattern connected to the side electrode;

soldering an electric part on a connecting conductor of the wiring pattern; and

decreasing a temperature of solder connecting the electric part to the connecting conductor from the side electrode to less than that to melt the solder when a temperature at the side electrode is high enough to melt the solder.

16. (New) The method according to claim 15, further comprising limiting the temperature of the solder by increasing a length of the connecting conductor.

17. (New) The method according to claim 15, further comprising increasing the length of the connecting conductor by including multiple bends between the electric part and the side electrode.

18. (New) The method according to claim 16, wherein the bends are perpendicular to each other.

19. (New) The method according to claim 16, wherein the bends have oblique angles with respect to each other.

20. (New) The method according to claim 16, wherein the connecting conductor has a total bend of at least 180°.